- No Frequency Compensation Required
- Low Power Consumption
- Short-Circuit Protection
- Offset-Voltage Null Capability
- Wide Common-Mode and Differential Voltage Ranges
- No Latch-Up
- Designed to Be Interchangeable With Fairchild μA747C and μA747M

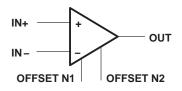
description

The uA747 is a dual general-purpose operational amplifier featuring offset-voltage null capability. Each half is electrically similar to uA741.

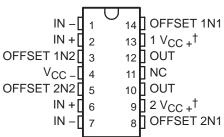
The high common-mode input voltage range and the absence of latch-up make this amplifier ideal for voltage-follower applications. The device is short-circuit protected and the internal frequency compensation ensures stability without external components. A low-value potentiometer may be connected between the offset null inputs to null out the offset voltage as shown in Figure 2.

The uA747C is characterized for operation from 0° C to 70° C; the uA747M is characterized for operation over the full military temperature range of -55° C to 125° C.

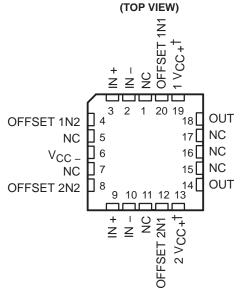
symbol (each amplifier)



D, J, N, OR W PACKAGE (TOP VIEW)



uA747m ... FK PACKAGE



NC - No internal connection

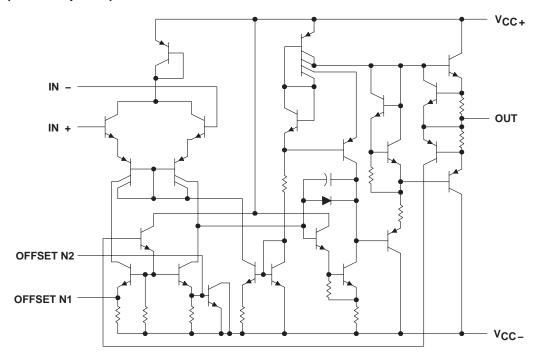
 † The two positive supply terminals (1 V_{CC +} and 2 V_{CC +}) are connected together internally.

AVAILABLE OPTIONS

	V. May		20-PIN			
TA	V _{IO} Max AT 25°C	SMALL OUTLINE (D)	CERAMIC DIP (J)	PLASTIC DIP (N)	FLAT PACK (W)	CHIP CARRIER (FK)
0°C						
to 70°C	6 mV	uA747CD	_	uA747CN	_	_
–55°C						
to 125°C	5 mV	_	uA747MJ	_	uA747MW	uA747MFK

The D package is available taped and reeled. Add the suffix R to the device type, (i.e., uA747CDR).

schematic (each amplifier)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

		uA747C	uA747M	UNIT
Supply voltage, V _{CC+} (see Note 1)	18	22	V	
Supply voltage, V _{CC} (see Note 1)		-18	-22	V
Differential input voltage (see Note 2)		±30	±30	V
Input voltage any input (see Notes 1 and 3)		±15	±15	V
Voltage between any offset null terminal (N1/N2) and V _{CC} _	±0.5	±0.5	V	
Duration of output short circuit (see Note 4)	unlimited	unlimited		
Continuous total dissipation	See Dissipation Rating Table			
Operating free-air temperature range		0 to 70	-55 to 125	°C
Storage temperature range		-65 to 150	-65 to 150	°C
Case temperature for 60 seconds	FK package		260	°C
Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds	J or W package		300	°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	D or N package	260		°C

- NOTES: 1. All voltage values, unless otherwise noted, are with respect to the midpoint between V_{CC} + and V_{CC} -.
 - 2. Differential voltages are at the noninverting input terminal with respect to the inverting input terminal.
 - 3. The magnitude of the input voltage must never exceed the magnitude of the supply voltage or 15 V, whichever is less.
 - 4. The output may be shorted to ground or either power supply. For the uA747M only, the unlimited duration of the short circuit applies at (or below) 125°C case temperature or 75°C free-air temperature.

DISSIPATION RATING TABLE

PACKAGE	$T_{\mbox{A}} \le 25^{\circ}\mbox{C}$ POWER RATING	DERATING FACTOR	DERATE ABOVE T _A	T _A = 70°C POWER RATING	T _A = 125°C POWER RATING
D	800 mW	7.6 mW/°C	45°C	608 mW	_
FK	800 mW	11.0 mW/°C	77°C	800 mW	275 mW
J	800 mW	11.0 mW/°C	77°C	800 mW	275 mW
N	800 mW	9.2 mW/°C	63°C	736 mW	_
W	800 mW	8.0 mW/°C	50°C	640 mW	200 mW



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electrical characteristics at specified free-air temperature, $V_{\mbox{CC}\pm}$ = $\pm 15~\mbox{V}$

	DADAMETED		T. T	uA747C			uA747M			LINUT	
PARAMETER		TEST CONDITIONS†	T _A ‡	MIN	TYP	MAX	MIN	TYP	MAX	UNIT	
V	Innut offset valtage	V- 0	25°C		1	6		1	5	mV	
VIO	Input offset voltage	V _O = 0	Full range			7.5			6	mv	
ΔVIO(adj)	Offset voltage adjust range		25°C		±15			±15		mV	
	lanut effect coment		25°C		20	200		20	200		
lio	Input offset current		Full range			300			500	nA	
1	Innut high current		25°C		80	500		80	500	Λ	
IB	Input bias current		Full range			800			1500	nA	
V	Common-mode		25°C	±12	±13		±12	±13		V	
VICR	input voltage range		Full range	±12			±12			V	
		R _L = 10 kΩ	25°C	24	28		24	28		.,	
V	Maximum peak-to-peak	$R_L \ge 10 \text{ k}\Omega$	Full range	24			24				
V _{O(PP)}	output voltage swing	R _L = 2 kΩ	25°C	20	26		20	26		V	
		$R_L \ge 2 k\Omega$	Full range	20			20				
	Large-signal differential	$R_L \ge 2 k\Omega$,	25°C	25	200		50	200		V/mV	
A_{VD}	voltage amplification	$V_0 = \pm 10 \text{ V}$	Full range	15			25				
rį	Input resistance		25°C	0.3	2		0.3*	2		MΩ	
r _o	Output resistance	See Note 5	25°C		75			75		Ω	
Ci	Input capacitance		25°C		1.4			1.4		pF	
CMRR	Common-mode	Vi Vi	25°C	70	90		70	90		dB	
CIVIKK	rejection ratio	V _{IC} = V _{ICR}	Full range	70			70			uБ	
ksvs	Supply-voltage s sensitivity VCC = ± 9 V to	V _{CC} = ± 9 V to ± 15 V	25°C		30	150		30	150	μV/V	
373	(ΔV _{IO} / ΔV _{CC})		Full range			150			150		
IOS	Short-circuit output current		25°C		±25	±40		±25	±40	mA	
Icc	Supply current	No lood	25°C		1.7	2.8		1.7	2.8	mA	
	(each amplifier)	No load	Full range			3.3			3.3		
D-	Power dissipation	No load Va O	25°C		50	85		50	85	\A/	
PD	(each amplifier)	No load, $V_O = 0$	Full range			100			100	mW	
V ₀₁ /V ₀₂	Channel separation		25°C		120			120	0	dB	

[†] All characteristics are measured under open-loop conditions with zero common-mode input voltage unless otherwise specified.

operating characteristics, V_{CC \pm} = \pm 15 V, T_A = 25°C

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _r	Rise time	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\		0.3		μs
	Overshoot factor	$V_I = 20 \text{ mV}, R_L = 2 \text{ k}\Omega, C_L = 100 \text{ pF}, \text{ See Figure 1}$		5%		
SR	Slew rate at unity gain	$V_I = 10 \text{ mV}, R_L = 2 \text{ k}\Omega, C_L = 100 \text{ pF}, \text{ See Figure 1}$		0.5		V/μs



 $[\]ddagger$ Full range for uA747C is 0°C to 70°C and for uA747M is -55°C to 125°C.

^{*}On products compliant to MIL-STD-883, Class B, this parameter is not production tested.

NOTE 5: This typical value applies only at frequencies above a few hundred hertz because of the effects of drift and thermal feedback.

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PARAMETER MEASUREMENT INFORMATION

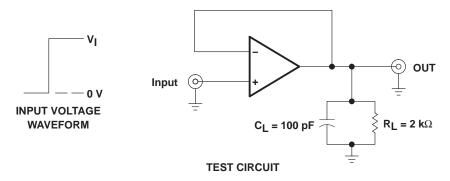


Figure 1. Rise Time, Overshoot, and Slew Rate

APPLICATION INFORMATION

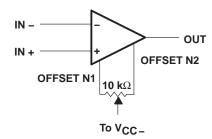


Figure 2. Input Offset Voltage Null Circuit

TYPICAL CHARACTERISTICS[†]

INPUT OFFSET CURRENT vs

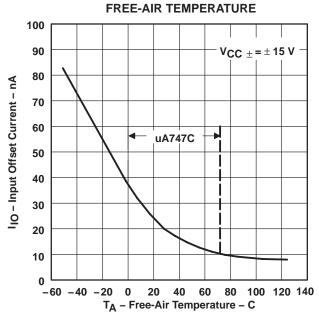


Figure 3

INPUT BIAS CURRENT

vs FREE-AIR TEMPERATURE

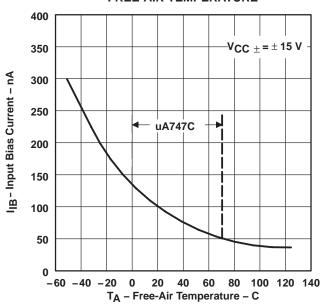


Figure 4

[†] Data at high and low temperatures are applicable only within the rated operating free-air temperature range of the particular devices.



TYPICAL CHARACTERISTICS

4

100

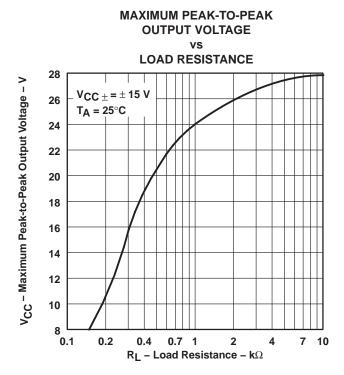
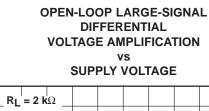


Figure 5



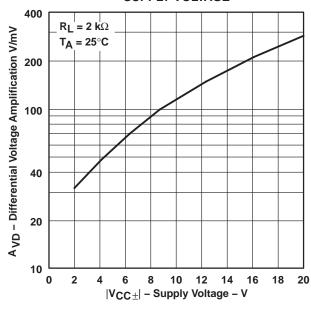


Figure 7

OUTPUT VOLTAGE FREQUENCY 40 VO(PP) - Maximum Peak-to-Peak Output Voltage - V V_{CC±} = ± 15 V 36 $R_L = 10 \text{ k}\Omega$ $T_A = 25^{\circ}\text{C}$ 32 28 24 20 16 12 8

MAXIMUM PEAK-TO-PEAK

Figure 6

OPEN-LOOP LARGE-SIGNAL DIFFERENTIAL VOLTAGE AMPLIFICATION

10 k

f - Frequency - Hz

100 k

1 M

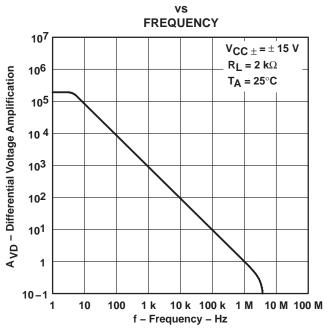
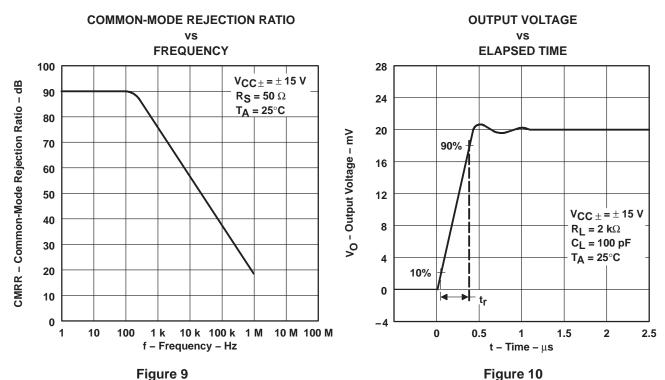
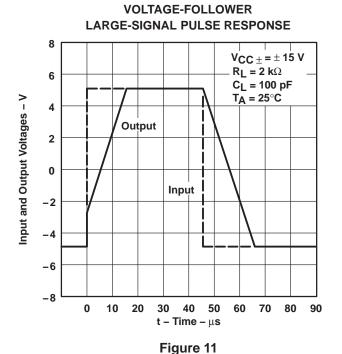


Figure 8

TYPICAL CHARACTERISTICS









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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
UA747-1MJ	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	Samples Not Available
UA747CD	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	Samples Not Available
UA747CD	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	Samples Not Available
UA747CDR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	Samples Not Available
UA747CDR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	Samples Not Available
UA747CN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Contact TI Distributor or Sales Office
UA747CN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Contact TI Distributor or Sales Office
UA747CNE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Contact TI Distributor or Sales Office
UA747CNE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Contact TI Distributor or Sales Office

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

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⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



PACKAGE OPTION ADDENDUM

7-Jun-2010

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14 LEADS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



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